

Appl. No. 10/616,528

Attorney Docket No. 10341-1847

I. Listing of Claims

1. (Currently Amended) A microelectronic package comprising:

a housing including a cylindrical wall defining a central axis, the cylindrical wall having an outer [[wall]] surface about an axis and an inner [[wall]] surface, said cylindrical wall defining a central compartment between the inner surface and the central axis, said inner [[wall]] surface having at least one assembly support surface that substantially faces the central axis, said housing further including at least one axial channel interposed between the outer [[wall]] surface and the inner [[wall]] surface; and

a microelectronic assembly affixed to the assembly support surface, thereby disposing the microelectronic assembly within the central compartment.

2. (Currently Amended) The microelectronic package of claim 1 wherein the inner [[wall]] surface is non-concentric with the outer [[wall]] surface.

3. (Original) The microelectronic package of claim 1 wherein the support surface is planar.

4. (Currently Amended) The microelectronic package of claim 1 wherein the inner [[wall]] surface comprises first and second assembly support surfaces that are planar, wherein the microelectronic package



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comprises a first microelectronic assembly affixed to the first assembly support surface, a second microelectronic assembly affixed to the second assembly support surface, and a flexible interconnect connecting the first microelectronic assembly and the second microelectronic assembly.

5. (Original) The microelectronic package of claim 1 wherein the channel is adapted for conveying cooling gas through the housing.

6. (Original) The microelectronic package of claim 1 wherein the housing comprises a first section having first axial edges and a second section having second axial edges joined to the first axial edges.

7. (Original) The microelectronic package of claim 6 wherein the first section comprises a semi-cylindrical wall and wherein the second section comprises a semi-cylindrical wall.

8. (Original) The microelectronic package of claim 1 wherein the housing is formed by a metal extrusion.

9. (Original) The microelectronic package of claim 1 wherein the housing is formed of a metal casting.

10. (Original) The microelectronic package of claim 1 wherein the housing is received in a tubular casing.

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11. (Original) The microelectronic package of claim 1 wherein the support surface is a curve having a radius of curvature less than the radius of the outer wall.

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